Guest editorial

EMPC/IMAPS 2017 Poland

The International Microelectronics and Packaging Society (IMAPS) Poland-Chapter was established in September 1982. It was formerly called the International Society for Hybrid Microelectronics-Poland Chapter, and since 1997, it was renamed as IMAPS Poland-Chapter. The IMAPS is a nonprofit-making organization whose aim is to spread knowledge relating to hybrid microelectronics, a key technology used in the assembly and application of semiconductors, thin-film circuits and printed circuit boards (PCBs) to form practical miniaturized electronic equipment. In 2008, the IMAPS collaborated with the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, thus forming the IMAPS-CPMT organization.

The 21st European Microelectronics and Packaging Conference, EMPC 2017, was organized together with its satellite conference, the 41st IMAPS Poland International Conference, under a common message "Where West meets East". This joint event took place on September 10-13, 2017, and it was organized by members of the IMAPS Poland-Chapter. The scope of the Conference covered everything in electronics between the chip and the system. The Conference was attended by 226 participants, including 165 guests from abroad. During the Conference, 5 keynote lectures, 87 invited lectures and 57 posters were presented. The Conference was supported by five international journals indexed in Journal Citation Report or Web of Science databases.

This year, similar to the previous year, two young scientists have been recognized and awarded a refund of their conference fees for the next IMAPS 2018 Poland Conference.

In this special issue of *Microelectronics International*, ten papers have been collected, covering the processes and procedures associated with low temperature co-fired ceramics (LTCC) technology, photovoltaics and light-emitting diode (LED) issues. All of them were subjected to the journal's regular reviewing procedure.

The first two papers by Malecha *et al.* and by Belavič *et al.* describe the application of LTCC elements to the fabrication of microfluidic structures. Third paper, by Tomaszewski *et al.*, treats a temperature transducer with frequency output, and fourth paper, by Dąbrowski *et al.*, deals with high-voltage applications in LTCC technology. In the next paper, Zuk *et al.* developed a capacitive film touch sensor by using different technologies, including LTCC, PCB and polymer technology. Meanwhile, Löffler *et al.* report about multilayer thick-film ceramic with laser microvias. The last paper related to LTCC technology, given by Ihle *et al.*, is a review article treating active eddy current turbocharger speed sensors.

Eighth and ninth papers (by Filipowski *et al.* and by Swatowska) discuss different problems in photovoltaics issue.

In the tenth paper, Grzesiak *et al.* present smart, high-colour rendering index LED lighting systems.

I would like to thank all the authors and reviewers for their scientific work and contributions that have led to the development and publication of this special issue of *Microelectronics International*. I hope that it will be of interest to the readers of the journal, and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about microelectronics issues. I believe that this branch of science should be further effectively developed in the future.

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